

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | | | | | |
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| NATURE OF CONVEYANCE: | ASSIGNMENT | | | | | | | | | | | | |
| CONVEYING PARTY DATA | | | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yaojian Lin</td> <td>05/28/2013</td> </tr> <tr> <td>Heinz-Peter Wirtz</td> <td>04/29/2013</td> </tr> <tr> <td>Seung Wook Yoon</td> <td>05/28/2013</td> </tr> <tr> <td>Pandi C. Marimuthu</td> <td>05/28/2013</td> </tr> </tbody> </table> | | Name | Execution Date | Yaojian Lin | 05/28/2013 | Heinz-Peter Wirtz | 04/29/2013 | Seung Wook Yoon | 05/28/2013 | Pandi C. Marimuthu | 05/28/2013 | | |
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| RECEIVING PARTY DATA | | | | | | | | | | | | | |
| <table border="1"> <tr> <td>Name:</td> <td>STATS ChipPAC, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>10 Ang Mo Kio Street 65</td> </tr> <tr> <td>Internal Address:</td> <td>#05-17/20 Techpoint</td> </tr> <tr> <td>City:</td> <td>Singapore</td> </tr> <tr> <td>State/Country:</td> <td>SINGAPORE</td> </tr> <tr> <td>Postal Code:</td> <td>569059</td> </tr> </table> | | Name: | STATS ChipPAC, Ltd. | Street Address: | 10 Ang Mo Kio Street 65 | Internal Address: | #05-17/20 Techpoint | City: | Singapore | State/Country: | SINGAPORE | Postal Code: | 569059 |
| Name: | STATS ChipPAC, Ltd. | | | | | | | | | | | | |
| Street Address: | 10 Ang Mo Kio Street 65 | | | | | | | | | | | | |
| Internal Address: | #05-17/20 Techpoint | | | | | | | | | | | | |
| City: | Singapore | | | | | | | | | | | | |
| State/Country: | SINGAPORE | | | | | | | | | | | | |
| Postal Code: | 569059 | | | | | | | | | | | | |
| PROPERTY NUMBERS Total: 1 | | | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13832809</td> </tr> </tbody> </table> | | Property Type | Number | Application Number: | 13832809 | | | | | | | | |
| Property Type | Number | | | | | | | | | | | | |
| Application Number: | 13832809 | | | | | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | | | | | |
| <p>Fax Number: 4804999456 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 480-499-9400 Email: main@plgaz.com Correspondent Name: PATENT LAW GROUP: Atkins & Associates Address Line 1: 605 W. Knox Road Address Line 2: Suite 104 Address Line 4: Tempe, ARIZONA 85284</p> | | | | | | | | | | | | | |
| ATTORNEY DOCKET NUMBER: | 2515.0414 | | | | | | | | | | | | |
| NAME OF SUBMITTER: | Robert D. Atkins | | | | | | | | | | | | |

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| Signature: | /Robert D. Atkins/ |
| Date: | 05/29/2013 |
| Total Attachments: 4 source=13832809ASSIGNMENTS#page1.tif source=13832809ASSIGNMENTS#page2.tif source=13832809ASSIGNMENTS#page3.tif source=13832809ASSIGNMENTS#page4.tif | |

ASSIGNMENT AND AGREEMENT

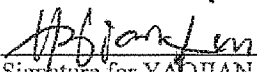
For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF DEPOSITING ENCAPSULANT ALONG SIDES AND SURFACE EDGE OF SEMICONDUCTOR DIE IN EMBEDDED WLCSP, which is described, illustrated, and claimed in U.S. Patent Application No. 13/832,809, filed March 15, 2013, and in U.S. Provisional Application No. 61/744,699, filed October 2, 2012, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



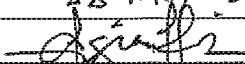
Signature for YAOJIAN LIN

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

28 MAY 2013


DIOSCORO MERILO

5 YISHUN STREET 23

SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

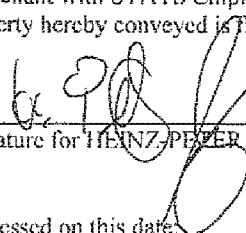
For good and valuable consideration, the receipt of which is hereby acknowledged, I, HEINZ-PETER WIRTZ of Switzerland, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF DEPOSITING ENCAPSULANT ALONG SIDES AND SURFACE EDGE OF SEMICONDUCTOR DIE IN EMBEDDED WLCSP, which is described, illustrated, and claimed in U.S. Patent Application No. 13/832,809, filed March 15, 2013, and in U.S. Provisional Application No. 61/744,699, filed October 2, 2012, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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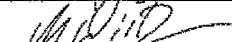
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Signature for HEINZ-PETER WIRTZ

Witnessed on this date:

29 April 2013

Signature of Witness:



Printed Name of Witness:

MARTINA WIRTZ

Address of Witness:

TERRAENSTR. 15A

5312 DÖTTINGEN, SWITZERLAND

PATENT

REEL: 030502 FRAME: 0716

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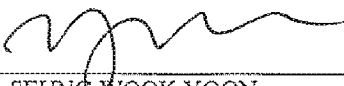
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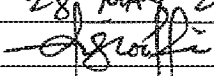
Signature for SEUNG WOOK YOON

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

28 MAY 2013

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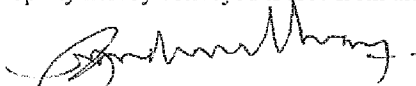
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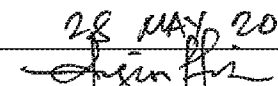
Signature for PANDI C. MARIMUTHU

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

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